

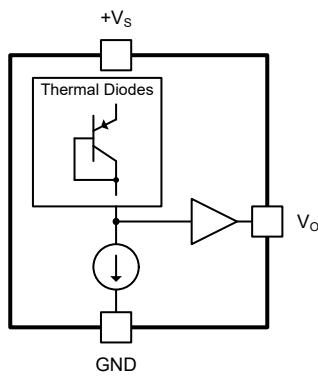
LM60 2.7V, SOT-23 或是 TO-92 温度传感器

1 特性

- 行业标准级传感器增益/偏移：
 - $6.25\text{mV/}^{\circ}\text{C}$, 0°C 下 424mV
- LM60B 温度精度：
 - 25°C 时 : $\pm 2^{\circ}\text{C}$ (最大值)
 - -25°C 到 $+125^{\circ}\text{C}$ 时 (旧芯片) 和 -40°C 到 $+125^{\circ}\text{C}$ (新芯片) 时 : $\pm 3^{\circ}\text{C}$ (最大值)
- LM60C 温度精度：
 - 25°C 时 : $\pm 3^{\circ}\text{C}$ (最大值)
 - -40°C 到 $+125^{\circ}\text{C}$ 时 : $\pm 4^{\circ}\text{C}$ (最大值)
- 宽电源电压范围 : 2.7V 至 10V
- 25°C 时的静态电流 : 110\mu A (最大值/旧芯片) 和 70\mu A (最大值/新芯片)
- 可用封装选项 :
 - SOT-23 (3 引脚)
 - TO-92 (3 引脚、直引线)
 - TO-92 (3 引脚、成型引线)
- 非线性度 : $\pm 0.8^{\circ}\text{C}$ (最大值)
- 输出直流阻抗 : 120Ω / 800Ω (典型值/最大值)
- 适用于远程应用

2 应用

- 手机、PC 和笔记本电脑
- 电源模块
- 电池管理
- 家用和多功能打印机
- HVAC 和固态硬盘
- 电器



简化版原理图

3 说明

LM60 器件是一种精密集成电路温度传感器，可在 2.7V 至 10V 单电源供电时检测 -40°C 至 $+125^{\circ}\text{C}$ 的温度范围。该器件的输出电压是与摄氏温度 ($6.25\text{mV/}^{\circ}\text{C}$) 成线性比例，并具有 424mV 的直流偏移量。该偏移量允许在无需负电源的情况下即可读取负温度。对于 -40°C 至 $+125^{\circ}\text{C}$ 的温度范围，此器件的额定输出电压范围介于 174mV 至 1205mV 之间。该器件经过校准，在室温下的精度为 $\pm 2^{\circ}\text{C}$ ，在全温度范围内的精度为 $\pm 3^{\circ}\text{C}$ 。其中旧芯片的温度范围为 -25°C 至 $+125^{\circ}\text{C}$ ，新芯片的温度范围为 -40°C 至 $+125^{\circ}\text{C}$ 。

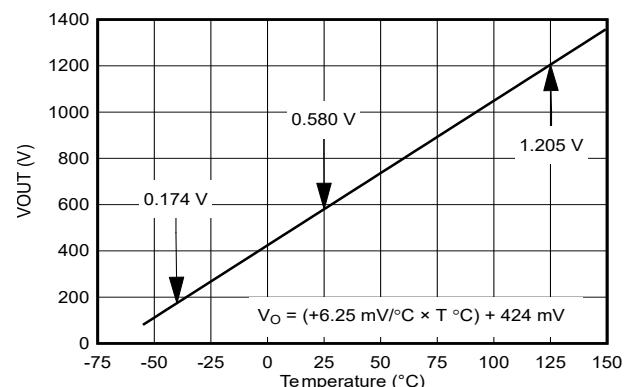
该器件的线性输出、 424mV 偏移量和工厂校准简化了在单电源环境中读取负温度所需的外部电路。由于器件的静态电流小于 110\mu A (旧芯片) 和 70\mu A (新芯片)，因此在 SOT-23 封装中，在静止空气中的自发热被限制在非常低的 0.1°C 。该器件本身就具备关断功能，因为其固有的低功耗特性使得该器件可直接通过许多逻辑门的输出供电。

封装信息

器件型号	封装 ⁽¹⁾	封装尺寸 ⁽²⁾
LM60	LP (TO-92 , 3)	$4.83\text{mm} \times 7.37\text{mm}$
	DBZ (SOT-23 , 3)	$2.37\text{mm} \times 2.92\text{mm}$

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。

(2) 封装尺寸 (长 \times 宽) 为标称值，并包括引脚 (如适用)。



$V_o = (+6.25\text{mV/}^{\circ}\text{C} \times T^{\circ}\text{C}) + 424\text{mV}$



本资源的原文使用英文撰写。为方便起见，TI 提供了译文；由于翻译过程中可能使用了自动化工具，TI 不保证译文的准确性。为确认准确性，请务必访问 ti.com 参考最新的英文版本 (控制文档)。

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4 Device Comparison

表 4-1. Device Comparison

ORDER NUMBER	PACKAGE	ACCURACY OVER TEMPERATURE	SPECIFIED TEMPERATURE RANGE
LM60BIM3X/NOPB	SOT-23 (DBZ) 3-pin	$\pm 3^\circ\text{C}$	$-25^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (Legacy chip)
			$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (New chip)
LM60CIM3X/NOPB		$\pm 4^\circ\text{C}$	$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$
LM60QIM3X/NOPB		$\pm 4^\circ\text{C}$	$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$
LM60BIZ/LFT3	TO-92 (LP) 3-pin Formed Leads	$\pm 3^\circ\text{C}$	$-25^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (Legacy chip)
			$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (New chip)
LM60BIZ/NOPB	TO-92 (LP) 3-pin Straight Leads	$\pm 3^\circ\text{C}$	$-25^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (Legacy chip)
			$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$ (New chip)
LM60CIZ/NOPB		$\pm 4^\circ\text{C}$	$-40^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$

(1) LM60B (Legacy chip) operates down to -40°C without damage but the accuracy is only verified from -25°C to 125°C .

表 4-2. Device Nomenclature

PRODUCT	OUT
LM60xlyyy/NOPB LM60xlyyy/LFT3	<p>x indicates that the device has B, C or Q (grade-1 device in accordance with the AEC-Q100 standard) variant. These devices can ship with the legacy chip (CSO: GF6 or SHE) or the new chip (CSO: RFB) with different <i>date code</i>. The reel packaging label provides date code information to distinguish which chip is being used. Device performance for new and legacy chips is denoted throughout the document.</p> <p>yyy indicates that the package type of the device which can be M3X/NOPB (SOT-23 3-pin) or Z/LFT3 (TO-92 3-pin Formed Leads) or Z/NOPB (TO-92 3-pin Straight Leads).</p> <p>For more information on TO-92 package options please see: TO-92 Packing Options / Ordering Instructions</p>

5 Pin Configuration and Functions

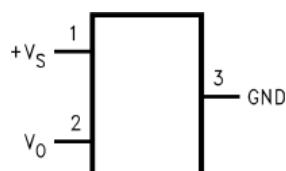


图 5-1. DBZ Package
3-Pin SOT-23
Top View

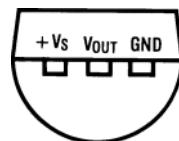


图 5-2. LP Package
3-Pin TO-92
(Formed Leads and Straight Leads)
Bottom View

表 5-1. Pin Functions

PIN			TYPE	DESCRIPTION
NAME	SOT-23	TO-92		
GND	3	3	GND	Device ground, connected to power supply negative terminal
V _{OUT}	2	2	O	Temperature sensor analog output
+V _S	1	1	POWER	Positive power supply pin

6 Specifications

6.1 Absolute Maximum Ratings

Over operating free-air temperature range unless otherwise noted⁽¹⁾

		MIN	MAX	UNIT
Supply voltage, $+V_S$	LM60	-0.2	12	V
Output voltage, V_O		-0.6	$+V_S + 0.6$	V
Output current, I_{OUT}			10	mA
Input current at any pin ⁽²⁾			5	mA
Maximum junction temperature, T_{JMAX}			125	°C
Storage temperature, T_{STG}		-65	150	°C

- Operation outside the *Absolute Maximum Ratings* may cause permanent device damage. *Absolute Maximum Ratings* do not imply functional operation of the device at these or any other conditions beyond those listed under *Recommended Operating Conditions*. If used outside the *Recommended Operating Conditions* but within the *Absolute Maximum Ratings*, the device may not be fully functional, and this may affect device reliability, functionality, performance, and shorten the device lifetime.
- When the input voltage (V_I) at any pin exceeds power supplies ($V_I < GND$ or $V_I > +V_S$), the current at that pin must be limited to 5mA.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$, Electrostatic discharge	LM60 (DBZ Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	
	LM60 (LP Package)	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2500	
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000	

- JEDEC document JEP155 states that 500V HBM allows safe manufacturing with a standard ESD control process.
- JEDEC document JEP157 states that 250V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
$+V_S$	Supply voltage	LM60	2.7	10	V
T_A , ($T_{MIN} \leqslant T_A \leqslant T_{MAX}$)	Specified temperature	LM60B	Legacy chip		-25 ⁽²⁾ 125
		LM60B	New chip		-40 125
		LM60C			-40 125

- Soldering process must comply with National Semiconductor's Reflow Temperature Profile specifications. Refer to www.national.com packaging. Reflow temperature profiles are different for lead-free and non-lead-free packages.
- LM60B (Legacy chip) operates down to -40°C without damage but the accuracy is only ensured from -25°C to 125°C.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		LM60				UNIT	
		DBZ (SOT-23) 3 PINS		LP (TO-92) 3 PINS			
		Legacy chip	New chip	Legacy chip	New chip		
$R_{\theta JA}$ ⁽²⁾	Junction-to-ambient thermal resistance	266	240.6	162	135.9	°C/W	
$R_{\theta JC}$ (top)	Junction-to-case (top) thermal resistance	135	144.5	85	109.1	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	59	72.3	-	108.9	°C/W	
Ψ_{JT}	Junction-to-top characterization parameter	18	28.7	29	24.6	°C/W	
Ψ_{JB}	Junction-to-board characterization parameter	58	71.7	142	108.9	°C/W	

- For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application note.

(2) The junction to ambient thermal resistance ($R_{\theta JA}$) is specified without a heat sink in still air.

6.5 Electrical Characteristics

Unless otherwise noted, these specifications apply for $+V_S = 3V$ (DC) and $I_{LOAD} = 1 \mu A$. All limits $T_A = T_J = 25^\circ C$ unless otherwise noted.

PARAMETER	TEST CONDITIONS		MIN ⁽¹⁾	TYP ⁽²⁾	MAX ⁽¹⁾	UNIT
SENSOR ACCURACY						
T_{ACY}	Temperature accuracy ⁽³⁾	LM60B ⁽⁴⁾		-2	2	°C
			$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-3	3	
	Temperature accuracy ⁽³⁾	LM60C		-3	3	
			$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-4	4	
SENSOR OUTPUT						
$V_{0^\circ C}$	Output voltage offset at $0^\circ C$			424		mV
T_C	Temperature coefficient (sensor gain)	LM60B	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	6.06	6.44	mV/°C
			$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	6	6.5	
		LM60C	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-0.6	0.6	
V_{ONL}	Output Nonlinearity ⁽⁵⁾	LM60B	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-0.8	0.8	°C
		LM60C	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-0.2		
Z_{OUT}	Output impedance			800		Ω
T_{LTD}	Long-term stability and drift ⁽⁶⁾	$T_J = T_{MAX} = 125^\circ C$ for 1000 hours			±0.2	°C
POWER SUPPLY						
I_{DD}	Operating current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip	82	110	μ A
			New chip	52	70	
			$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$ Legacy chip		125	
			$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$ New chip		90	
PSR	Line regulation ⁽⁷⁾	LM60, $2.7V \leq +V_S \leq 3.3V$	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-2.3	2.3	mV
		LM60, $3V \leq +V_S \leq 10V$	$T_A = T_J = T_{MIN} \text{ to } T_{MAX}$	-0.3	0.3	mV/V
ΔI_{DD}	Change of quiescent current	LM60, $2.7V \leq +V_S \leq 10V$	Legacy chip	±5		μ A
			New chip	±6.5		
I_{DD_TEM}	Temperature coefficient of quiescent current				0.2	μ A/°C

- (1) Limits are specified to TI's AOQL (Average Outgoing Quality Level).
- (2) Typicals are at $T_J = T_A = 25^\circ C$ and represent most likely parametric norm.
- (3) Accuracy is defined as the error between the output voltage and $6.25\text{mV/}^\circ C$ times the case temperature of the device plus 424mV, at specified conditions of voltage, current, and temperature (expressed in °C).
- (4) LM60B (Legacy chip) operates down to $-40^\circ C$ without damage but the accuracy is only verified from $-25^\circ C$ to $125^\circ C$. However, LM60B (New chip) specs are verified from $-40^\circ C$ to $125^\circ C$.
- (5) Nonlinearity is defined as the deviation of the output-voltage-versus-temperature curve from the best-fit straight line, over the rated temperature rating of the device
- (6) For best long-term stability, any precision circuit provides the best results if the unit is aged at a warm temperature, temperature cycled for at least 46 hours before long-term life test begins for both temperatures. This is especially true when a small (surface-mount) part is wave soldered; allow time for stress relaxation to occur. The majority of the drift will occur in the first 1000 hours at elevated temperatures. The drift after 1000 hours will not continue at the first 1000 hour rate.
- (7) Regulation is measured at constant junction temperature, using pulse testing with a low duty cycle. Changes in output due to heating effects can be computed by multiplying the internal dissipation by the thermal resistance

6.6 Typical Characteristics

To generate these curves, the device is mounted to a printed-circuit board as shown in [图 8-9](#) or [图 8-10](#).

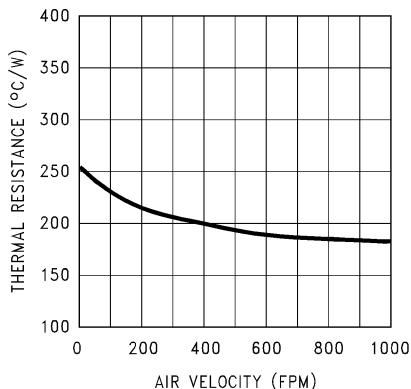


图 6-1. Thermal Resistance Junction to Air (Legacy chip)

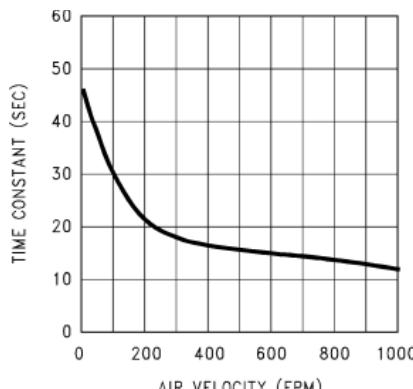


图 6-2. Thermal Time Constant (Legacy chip)

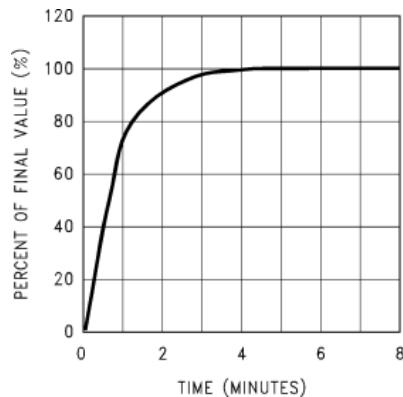


图 6-3. Thermal Response in Still Air With Heat Sink (Legacy chip)

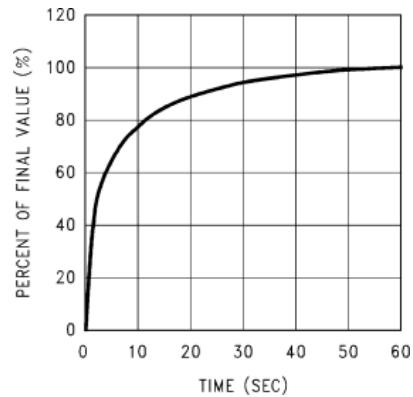


图 6-4. Thermal Response in Stirred Oil Bath With Heat Sink (Legacy chip)

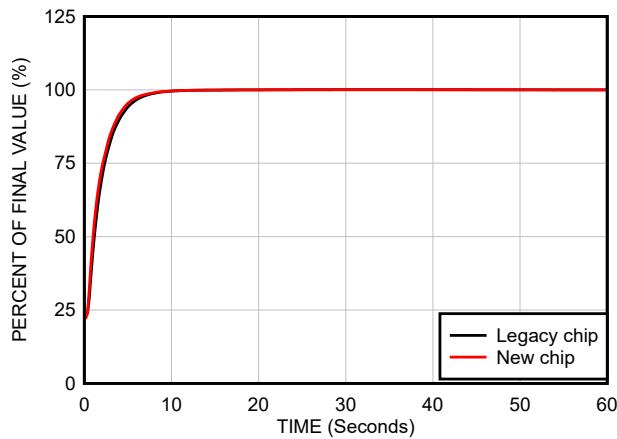


图 6-5. Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches x 0.5 inches PCB board)

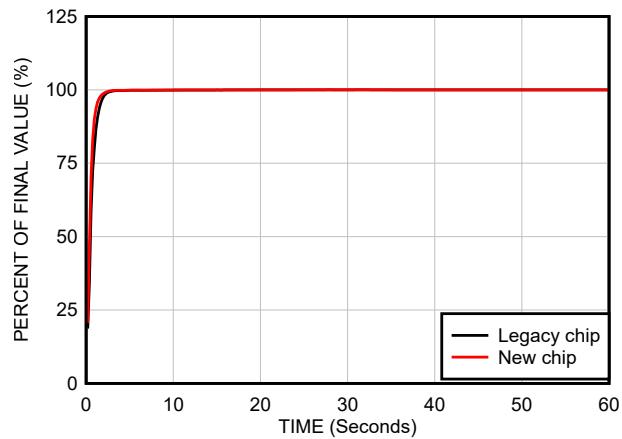


图 6-6. Thermal Response in Stirred Oil Bath Without Heat Sink

6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [图 8-9](#) or [图 8-10](#).

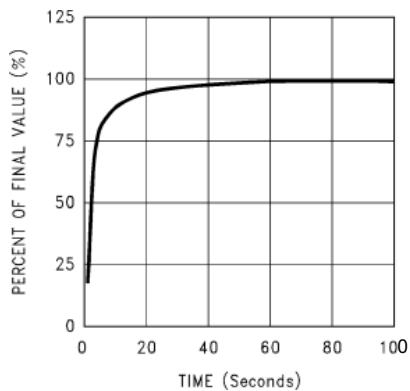


图 6-7. Thermal Response in Still Air Without a Heat Sink
(Legacy chip)

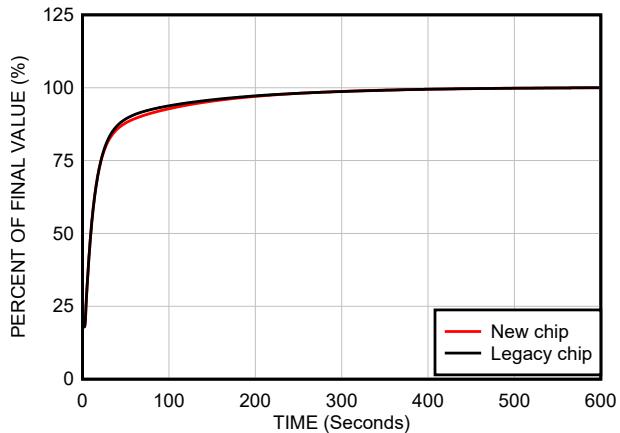


图 6-8. Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip in the new test setup)

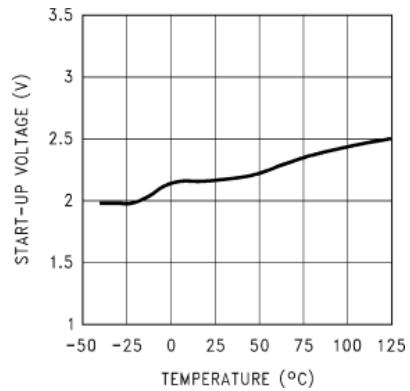


图 6-9. Start-Up Voltage vs Temperature (Legacy chip)

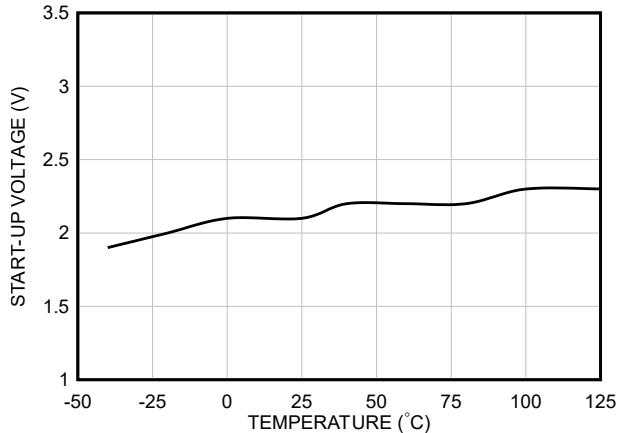


图 6-10. Start-Up Voltage vs Temperature (New chip)

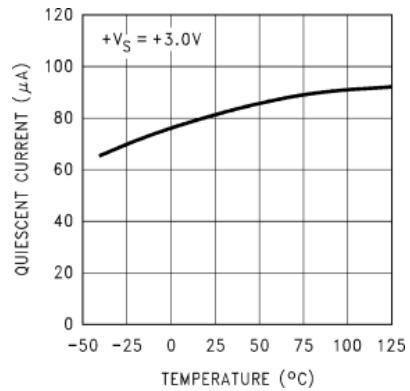


图 6-11. Quiescent Current vs Temperature (Legacy chip)

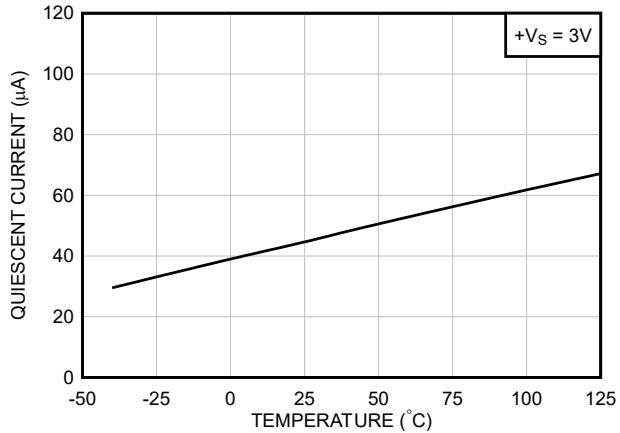


图 6-12. Quiescent Current vs Temperature (New chip)

6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [图 8-9](#) or [图 8-10](#).

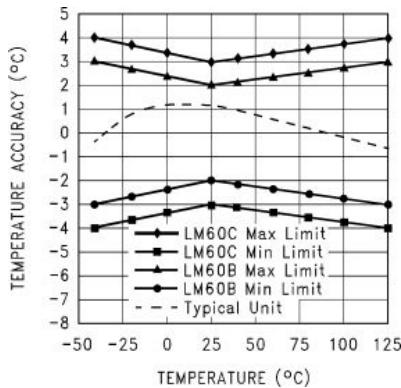


图 6-13. Accuracy vs Temperature (Legacy chip)

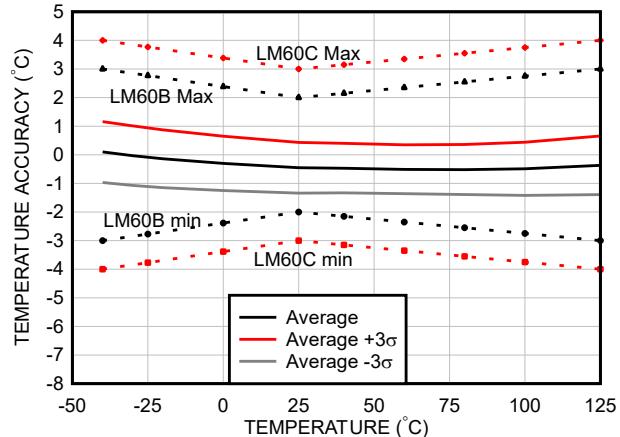


图 6-14. Accuracy vs Temperature (New chip)

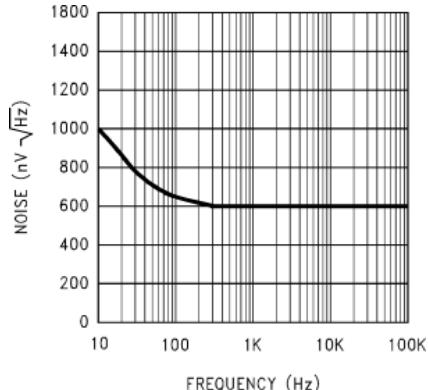


图 6-15. Noise Voltage (Legacy chip)

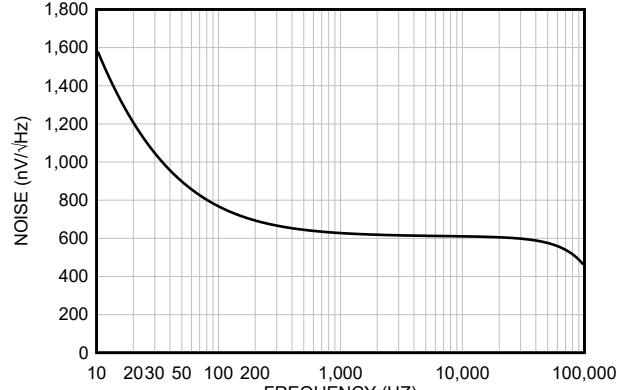


图 6-16. Noise Voltage (New chip)

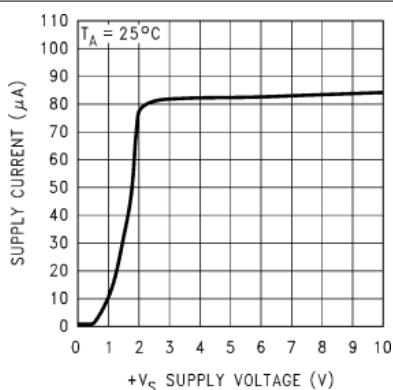


图 6-17. Supply Current vs Supply Voltage (Legacy chip)

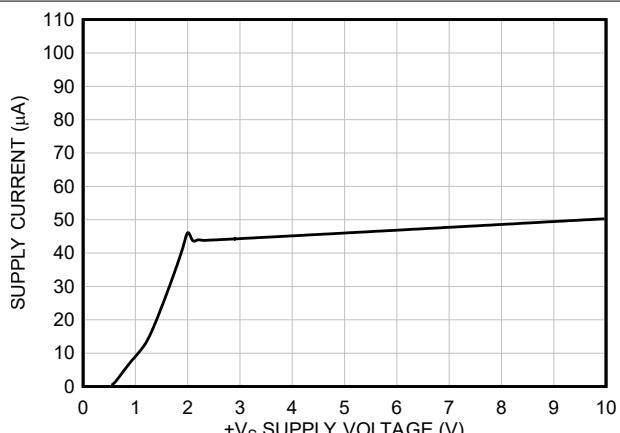
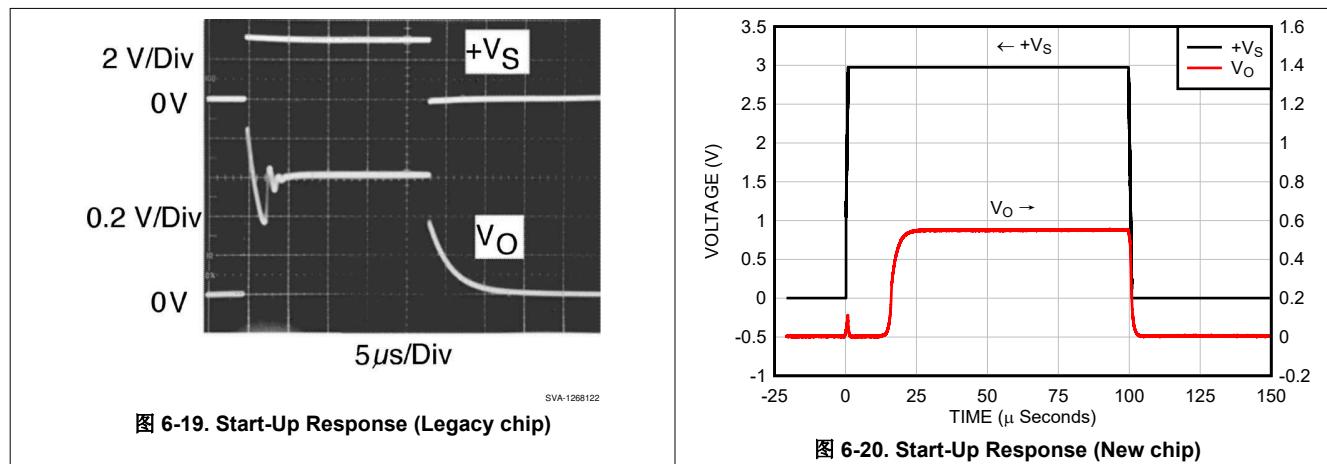


图 6-18. Supply Current vs Supply Voltage (New chip)

6.6 Typical Characteristics (continued)

To generate these curves, the device is mounted to a printed-circuit board as shown in [图 8-9](#) or [图 8-10](#).



7 Detailed Description

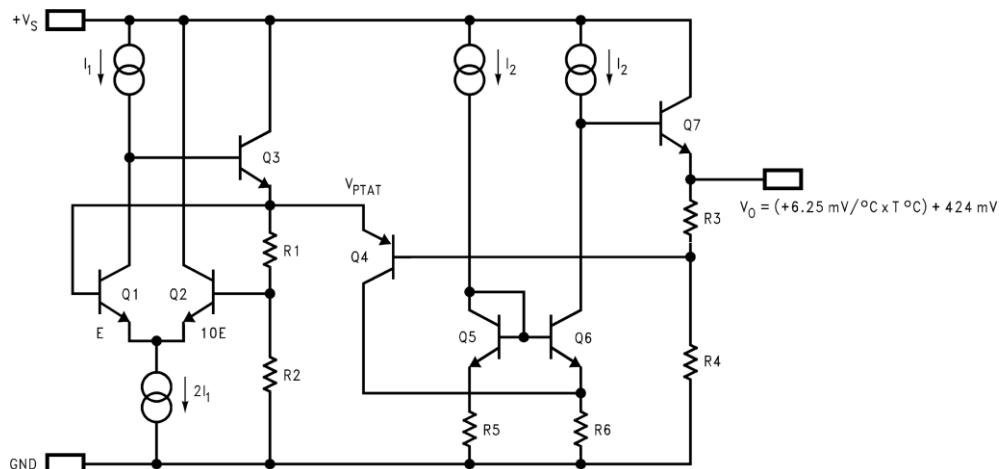
7.1 Overview

The LM60 device is a precision analog bipolar temperature sensor that can sense a -40°C to $+125^{\circ}\text{C}$ temperature range while operating from a single 2.7V supply. The output voltage of the LM60 is linearly proportional to Celsius (Centigrade) temperature ($6.25\text{mV/}^{\circ}\text{C}$) and has a DC offset of 424mV. The offset allows reading negative temperatures with a single positive supply. The nominal output voltage of the device ranges from 174mV to 1205mV for a -40°C to $+125^{\circ}\text{C}$ temperature range. The device is calibrated to provide accuracies of $\pm 2.0^{\circ}\text{C}$ at room temperature and $\pm 3^{\circ}\text{C}$ over the full -25°C to $+125^{\circ}\text{C}$ (for Legacy chip) or -40°C to $+125^{\circ}\text{C}$ (for New chip) temperature range.

With a quiescent current of the device is less than $110\text{ }\mu\text{A}$ (for Legacy chip) and $70\text{ }\mu\text{A}$ (for New chip), self-heating is limited to a very low 0.1°C in still air in the SOT-23 package. Shutdown capability for the device is intrinsic because the inherent low power consumption allows the device to be powered directly from the output of many logic gates.

The output of the LM60 is a Class A base emitter follower, thus the LM60 can source quite a bit of current while sinking less than $1\mu\text{A}$. In any event load current must be minimized to limit the contribution to the total temperature error.

7.2 Functional Block Diagram



7.3 Feature Description

7.3.1 LM60 Transfer Function

The LM60 follows a simple linear transfer function to achieve the accuracy as listed in [Fig 6.5](#) as given:

$$V_O = (6.25\text{mV/}^{\circ}\text{C} \times T \text{ }^{\circ}\text{C}) + 424\text{mV} \quad (1)$$

where

- T is the temperature
- V_O is the LM60 output voltage

7.4 Device Functional Modes

The only functional mode for this device is an analog output directly proportional to temperature.

8 Application and Implementation

备注

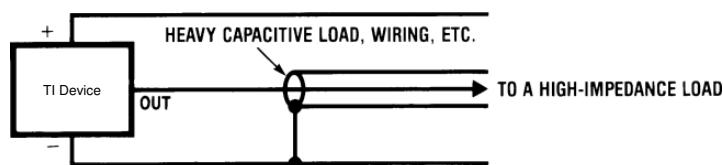
以下应用部分中的信息不属于 TI 器件规格的范围，TI 不担保其准确性和完整性。TI 的客户应负责确定器件是否适用于其应用。客户应验证并测试其设计，以确保系统功能。

8.1 Application Information

The device has a low supply current and a wide supply range, therefore it can easily be driven by a battery.

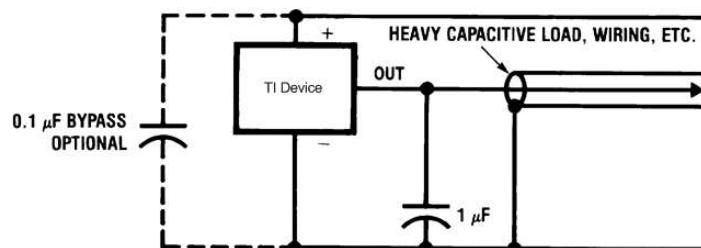
8.1.1 Capacitive Loads

The device handles capacitive loading well. Without any special precautions, the device can drive any capacitive load as shown in [图 8-1](#). Over the specified temperature range the device has a maximum output impedance of 800Ω . In an extremely noisy environment, adding some filtering to minimize noise pick-up can be required. TI recommends that $0.1\mu F$ be added from $+V_S$ to GND to bypass the power supply voltage, as shown in [图 8-2](#). In a noisy environment, adding a capacitor from the output to ground can be required. A $1\mu F$ output capacitor with the 800Ω output impedance forms a 199Hz, low-pass filter. Because the thermal time constant of the device is much slower than the 6.3ms time constant formed by the RC, the overall response time of the device is not significantly affected. For much larger capacitors, this additional time lag increases the overall response time of the device.



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图 8-1. No Decoupling Required for Capacitive Load



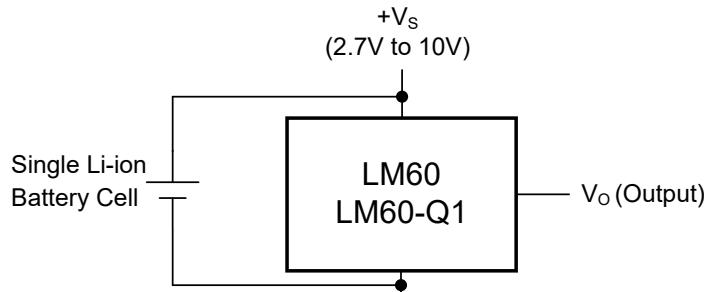
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图 8-2. Filter Added for Noisy Environment

8.2 Typical Applications

8.2.1 Full-Range Centigrade Temperature Sensor

Because the LM60 is a simple temperature sensor that provides an analog output, design requirements related to the layout are also important. Refer to [图 8.5](#) for details.



$$V_O = (6.25\text{mV/}^\circ\text{C} \times T^\circ\text{C}) + 424\text{mV}$$

图 8-3. Full-Range Centigrade Temperature Sensor (-40°C to +125°C) Operating From a Single Li-Ion Battery Cell

8.2.1.1 Design Requirements

For this design example, use the design parameters listed in [表 8-1](#).

表 8-1. Temperature and Typical V_O Values of 图 8-3

TEMPERATURE (T)	TYPICAL V _O
125°C	1205mV
100°C	1049mV
25°C	580mV
0°C	424mV
- 25°C	268mV
- 40°C	174mV

8.2.1.2 Detailed Design Procedure

Selection of the LM60 is based on the output voltage transfer function being able to meet the needs of the rest of the system.

8.2.1.3 Application Curve

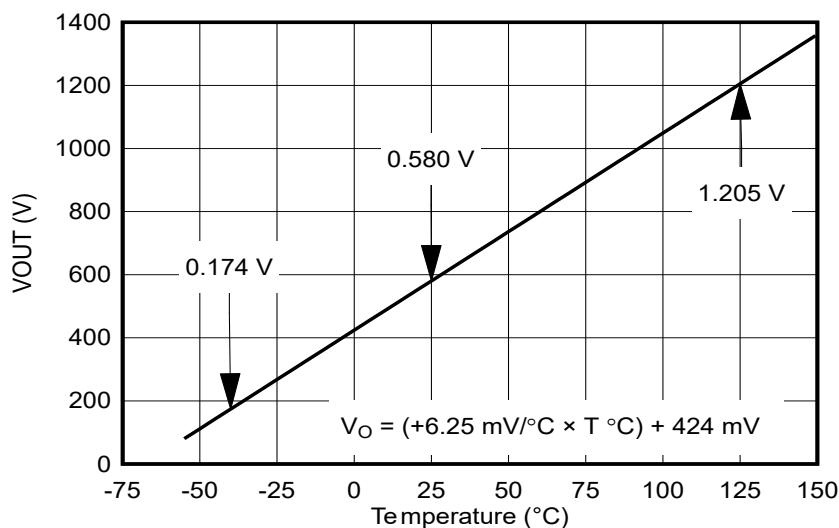
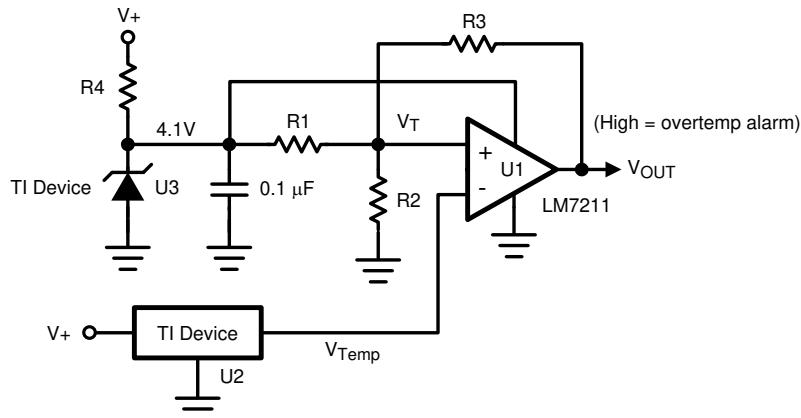


图 8-4. LM60 Output Transfer Function

8.2.2 Centigrade Thermostat Application



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图 8-5. Centigrade Thermostat

8.2.2.1 Design Requirements

A simple thermostat can be created by using a reference (LM4040) and a comparator (LM7211 or LMC7211-N) as shown in [图 8-5](#).

8.2.2.2 Detailed Design Procedure

Use [方程式 2](#) and [方程式 3](#) to calculate the threshold values for T1 and T2.

$$V_{T1} = \frac{(4.1)R2}{R2 + R1||R3} \quad (2)$$

$$V_{T2} = \frac{(4.1)R2||R3}{R1 + R2||R3} \quad (3)$$

8.2.2.3 Application Curve

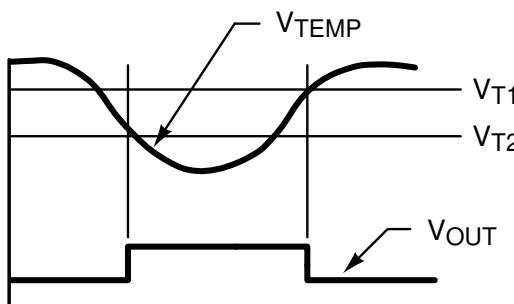
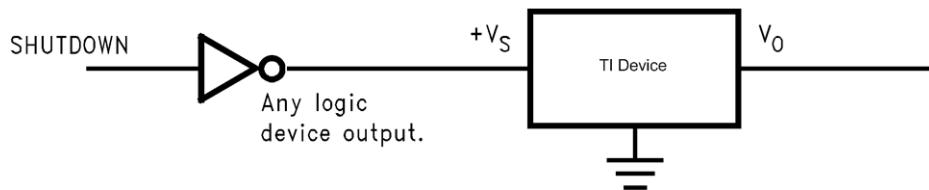


图 8-6. Thermostat Output Waveform

8.3 System Examples

8.3.1 Conserving Power Dissipation With Shutdown

The LM60 draws very little power, therefore the device can simply be shutdown by driving the LM60 supply pin with the output of a logic gate as shown in [图 8-7](#).



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图 8-7. Conserving Power Dissipation With Shutdown

8.4 Power Supply Recommendations

In an extremely noisy environment, add some filtering to minimize noise pick-up. Adding $0.1 \mu F$ from $+V_S$ to GND is recommended to bypass the power supply voltage, as shown in [图 8-2](#). In a noisy environment, add a capacitor from the output to ground.

8.5 Layout

8.5.1 Layout Guidelines

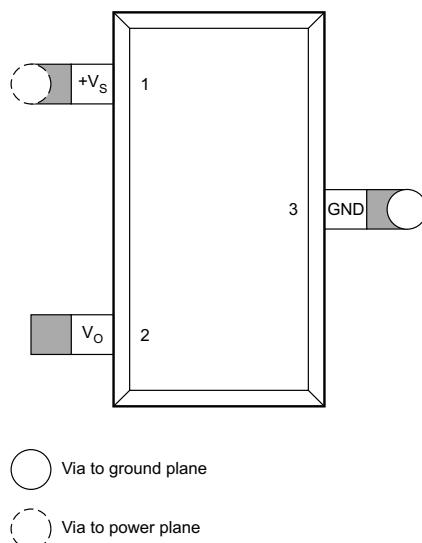
The LM60 can be applied easily in the same way as other integrated-circuit temperature sensors. The device can be glued or cemented to a surface. The temperature that the LM60 is sensing is within approximately $+0.1^\circ C$ of the surface temperature that the leads of the LM60 are attached to.

This presumes that the ambient air temperature is almost the same as the surface temperature. If the air temperature is much higher or lower than the surface temperature, the actual temperature of the device die is at an intermediate temperature between the surface temperature and the air temperature.

To provide good thermal conductivity, the backside of the device die is directly attached to the GND pin. The lands and traces to the device are part of the printed-circuit board, which is the object whose temperature is being measured. These printed-circuit board lands and traces do not cause the temperature of the device to deviate from the desired temperature.

Alternatively, the device can be mounted inside a sealed-end metal tube, and can then be dipped into a bath or screwed into a threaded hole in a tank. As with any IC, the device and accompanying wiring and circuits must be kept insulated and dry to avoid leakage and corrosion. Specifically when the device operates at cold temperatures where condensation can occur. Printed-circuit coatings and varnishes such as a conformal coating and epoxy paints or dips are often used to verify that moisture cannot corrode the device or connections.

8.5.2 Layout Example



1/2-inch square printed circuit board with 2-oz. copper foil or similar.

图 8-8. PCB Layout

8.5.3 Thermal Considerations

The thermal resistance junction to ambient ($R_{\theta JA}$) is the parameter used to calculate the rise of a device junction temperature due to the device power dissipation. Use [方程式 4](#) to calculate the rise in the die temperature of the device.

$$T_J = T_A + R_{\theta JA} [(+V_S I_Q) + (+V_S - V_O) I_L] \quad (4)$$

where

- I_Q is the quiescent current
- I_L is the load current on the output

[表 8-2](#) summarizes the rise in die temperature of the LM60 without any loading, and the thermal resistance for different conditions. The values in [表 8-2](#) were actually measured where as the values shown in [节 6.4](#) were calculated using modeling methods as described in the [Semiconductor and IC Package Thermal Metrics](#) (SPRA953) application report.

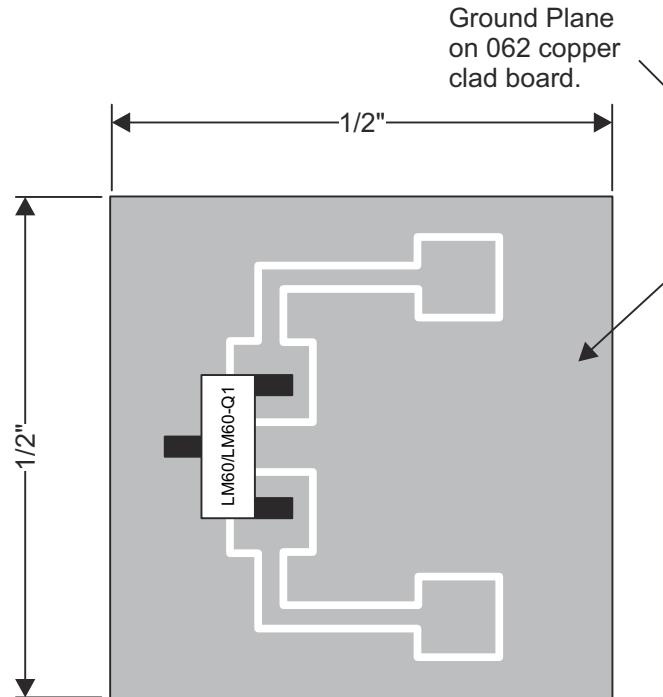
表 8-2. Temperature Rise of LM60 Due to Self-Heating and Thermal Resistance ($R_{\theta JA}$)

	SOT-23 ⁽¹⁾ NO HEAT SINK		SOT-23 ⁽²⁾ SMALL HEAT FIN		TO-92 ⁽¹⁾ NO HEAT FIN		TO-92 ⁽³⁾ SMALL HEAT FIN	
	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$	$R_{\theta JA}$	$T_J - T_A$
	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)	(°C/W)	(°C)
Still air Legacy chip	450	0.17	260	0.1	180	0.07	140	0.05
Moving air Legacy chip	—	—	180	0.07	90	0.034	70	0.026

(1) Part soldered to 30 gauge wire.

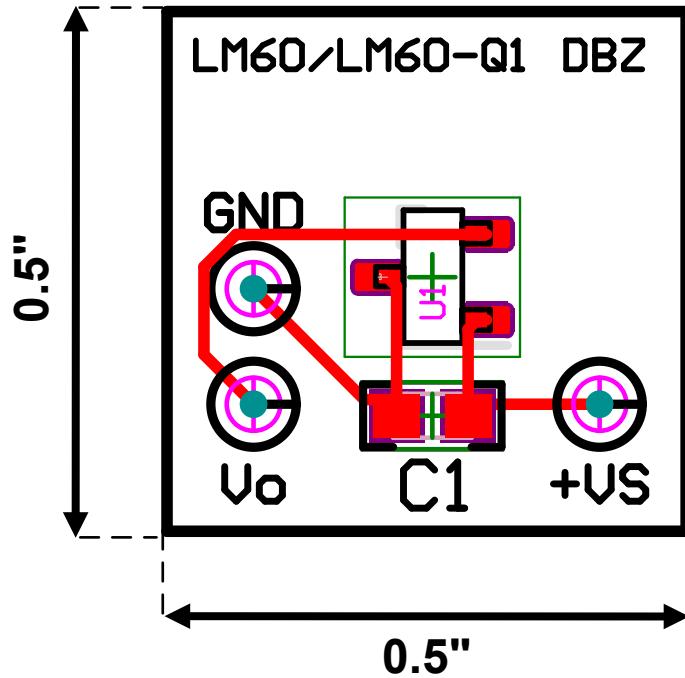
(2) Heat sink used is 1/2-in square printed-circuit board with 2-oz. foil with part attached as shown in [图 8-9](#).

(3) Part glued or leads soldered to 1-in square of 1/16-in printed-circuit board with 2-oz. foil or similar.



1/2-in Square Printed-Circuit Board with 2oz. Copper Foil or Similar.

图 8-9. Printed-Circuit Board Used for Heat Sink to Generate Thermal Response Curves (Legacy chip)



1/2in Square Printed-Circuit Board with FR-4 material.

图 8-10. Printed-Circuit Board Used to Generate Thermal Response Curves (New Test Setup for Both New Chip and Legacy Chip)

9 Device and Documentation Support

9.1 Documentation Support

9.1.1 Related Documentation

For related documentation see the following:

- Texas Instruments, [LM50 and LM50-Q1 SOT-23 Single-Supply Centigrade Temperature Sensor](#), data sheet
- Texas Instruments, [TMP23x Low-Power, High-Accuracy Analog Output Temperature Sensors](#), data sheet
- Texas Instruments, [LM60 Evaluation Module](#), EVM user's guide
- Texas Instruments, [LM60-Q1 Functional Safety FIT Rate and FMD](#), Functional safety information.

9.2 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](#) 上的器件产品文件夹。点击 [通知](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

9.3 支持资源

[TI E2E™ 中文支持论坛](#)是工程师的重要参考资料，可直接从专家处获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题，获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的[使用条款](#)。

9.4 Trademarks

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9.5 静电放电警告



静电放电 (ESD) 会损坏这个集成电路。德州仪器 (TI) 建议通过适当的预防措施处理所有集成电路。如果不遵守正确的处理和安装程序，可能会损坏集成电路。

ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

9.6 术语表

TI 术语表

本术语表列出并解释了术语、首字母缩略词和定义。

10 Revision History

Changes from Revision F (August 2017) to Revision G (February 2025)	Page
• 更新了整个文档中的表格、图和交叉参考的编号格式.....	1
• Updated the <i>Device Comparison</i> section with existing OPNs and adding <i>Device Nomenclature</i> table.....	3
• Changed Machine model (MM) Electrostatic discharge to Charged-device model (CDM).....	4
• Changed minimum specified temperature for LM60B from -25°C to -40°C in the New chip.....	4
• Changed DBZ and LP packages Thermal Information section. in the New chip.....	4
• Added “operating current” and “Change of quiescent current” for the New chip.....	5
• Added graphs for new chip, reordered and corrected the graphs for legacy chip.....	6
• Added corrections to the <i>Thermal Resistance Junction to Air (Legacy chip)</i> graph.....	6
• Added <i>Thermal Response in Stirred Oil Bath With Heat Sink (0.5 inches × 0.5 inches PCB board)</i> graph for both Legacy and New chips.....	6
• Added <i>Thermal Response in Still Air Without a Heat Sink (Both Legacy and New chip together in a new test setup)</i> graph for both Legacy and New chips.....	6

- Added the *Start-Up Voltage vs Temperature*, *Quiescent Current vs Temperature*, *Accuracy vs Temperature*, *Noise Voltage*, *Supply Current vs Supply Voltage* and *Start-Up Response* graphs for New chip..... 6

Changes from Revision E (September 2015) to Revision F (August 2017)	Page
--	------

• 将汽车器件移到了单独的数据表 (SNIS197) 中.....	1
• Added table note for the LM60B.....	3

Changes from Revision D (November 2012) to Revision E (November 2014)	Page
---	------

• 添加了引脚配置和功能部分、ESD 等级表、特性说明部分、器件功能模式、应用和实施部分、电源相关建议部分、布局部分、器件和文档支持部分以及机械、封装和可订购信息部分.....	1
--	---

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
LM60BIM3	NRND	Production	SOT-23 (DBZ) 3	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3.B	NRND	Production	SOT-23 (DBZ) 3	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3/NOPB	Obsolete	Production	SOT-23 (DBZ) 3	-	-	Call TI	Call TI	-25 to 125	T6B
LM60BIM3X	NRND	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X.B	NRND	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X/NOPB	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X/NOPB.A	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIM3X/NOPB.B	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 125	T6B
LM60BIZ/LFT3	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/LFT3.A	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/LFT3.B	Active	Production	TO-92 (LP) 3	2000 LARGE T&R	Yes	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/NOPB	Active	Production	TO-92 (LP) 3	1800 SMALL T&R	-	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60BIZ/NOPB.A	Active	Production	TO-92 (LP) 3	1800 SMALL T&R	-	SN	N/A for Pkg Type	-25 to 125	(LM60, LM60BIZ) BIZ
LM60CIM3	NRND	Production	SOT-23 (DBZ) 3	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3.B	NRND	Production	SOT-23 (DBZ) 3	1000 SMALL T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3/NOPB	Obsolete	Production	SOT-23 (DBZ) 3	-	-	Call TI	Call TI	-40 to 125	T6C
LM60CIM3X	NRND	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X.B	NRND	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	No	SNPB	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X/NOPB	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X/NOPB.A	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIM3X/NOPB.B	Active	Production	SOT-23 (DBZ) 3	3000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	T6C
LM60CIZ/NOPB	Active	Production	TO-92 (LP) 3	1800 SMALL T&R	-	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60CIZ) CIZ
LM60CIZ/NOPB.A	Active	Production	TO-92 (LP) 3	1800 SMALL T&R	-	SN	N/A for Pkg Type	-40 to 125	(LM60, LM60CIZ) CIZ

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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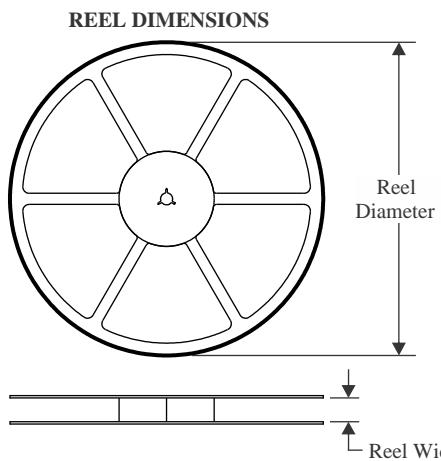
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF LM60 :

- Automotive : [LM60-Q1](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

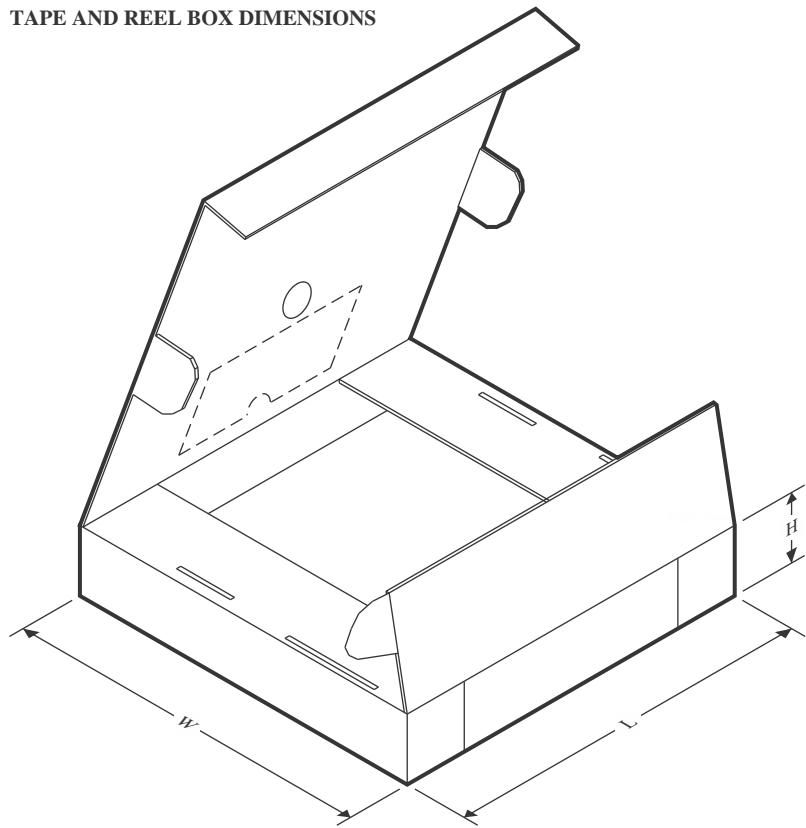
TAPE AND REEL INFORMATION


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	178.0	8.4	3.3	2.9	1.22	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM60BIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0
LM60CIM3X/NOPB	SOT-23	DBZ	3	3000	208.0	191.0	35.0

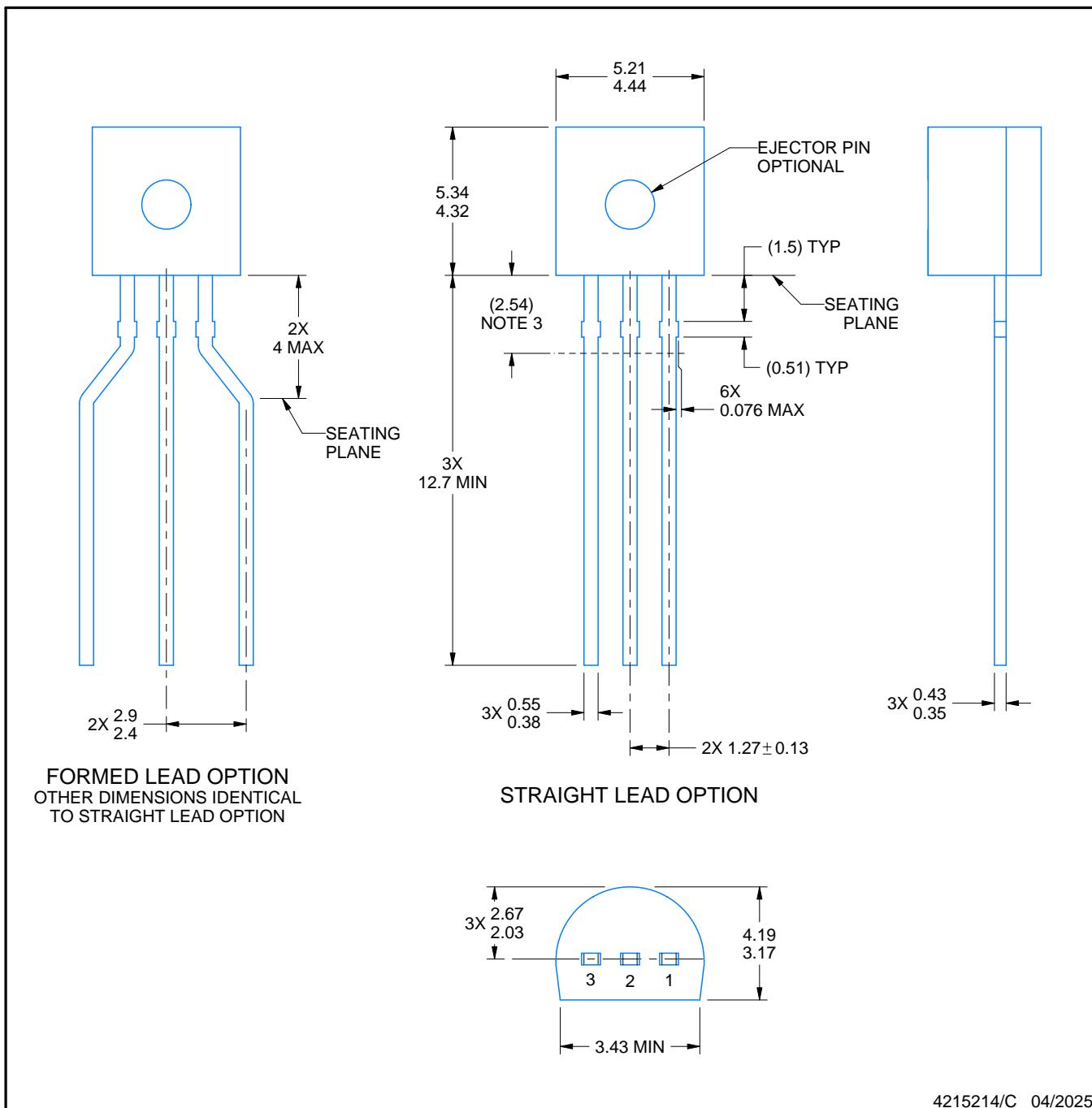
PACKAGE OUTLINE

LP0003A



TO-92 - 5.34 mm max height

TO-92



4215214/C 04/2025

NOTES:

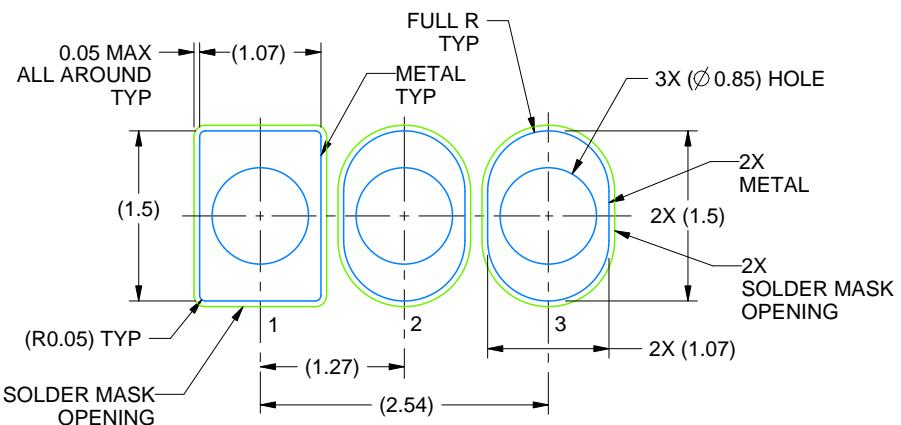
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Lead dimensions are not controlled within this area.
4. Reference JEDEC TO-226, variation AA.
5. Shipping method:
 - a. Straight lead option available in bulk pack only.
 - b. Formed lead option available in tape and reel or ammo pack.
 - c. Specific products can be offered in limited combinations of shipping medium and lead options.
 - d. Consult product folder for more information on available options.

EXAMPLE BOARD LAYOUT

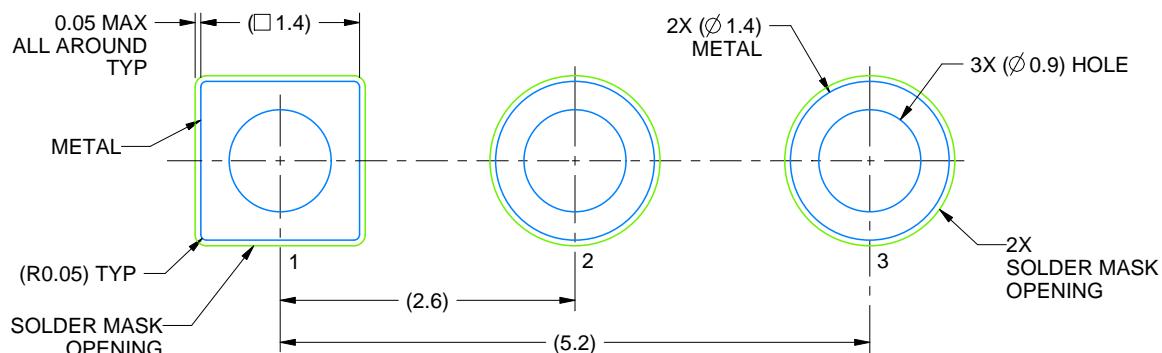
LP0003A

TO-92 - 5.34 mm max height

TO-92



LAND PATTERN EXAMPLE
STRAIGHT LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X



LAND PATTERN EXAMPLE
FORMED LEAD OPTION
NON-SOLDER MASK DEFINED
SCALE:15X

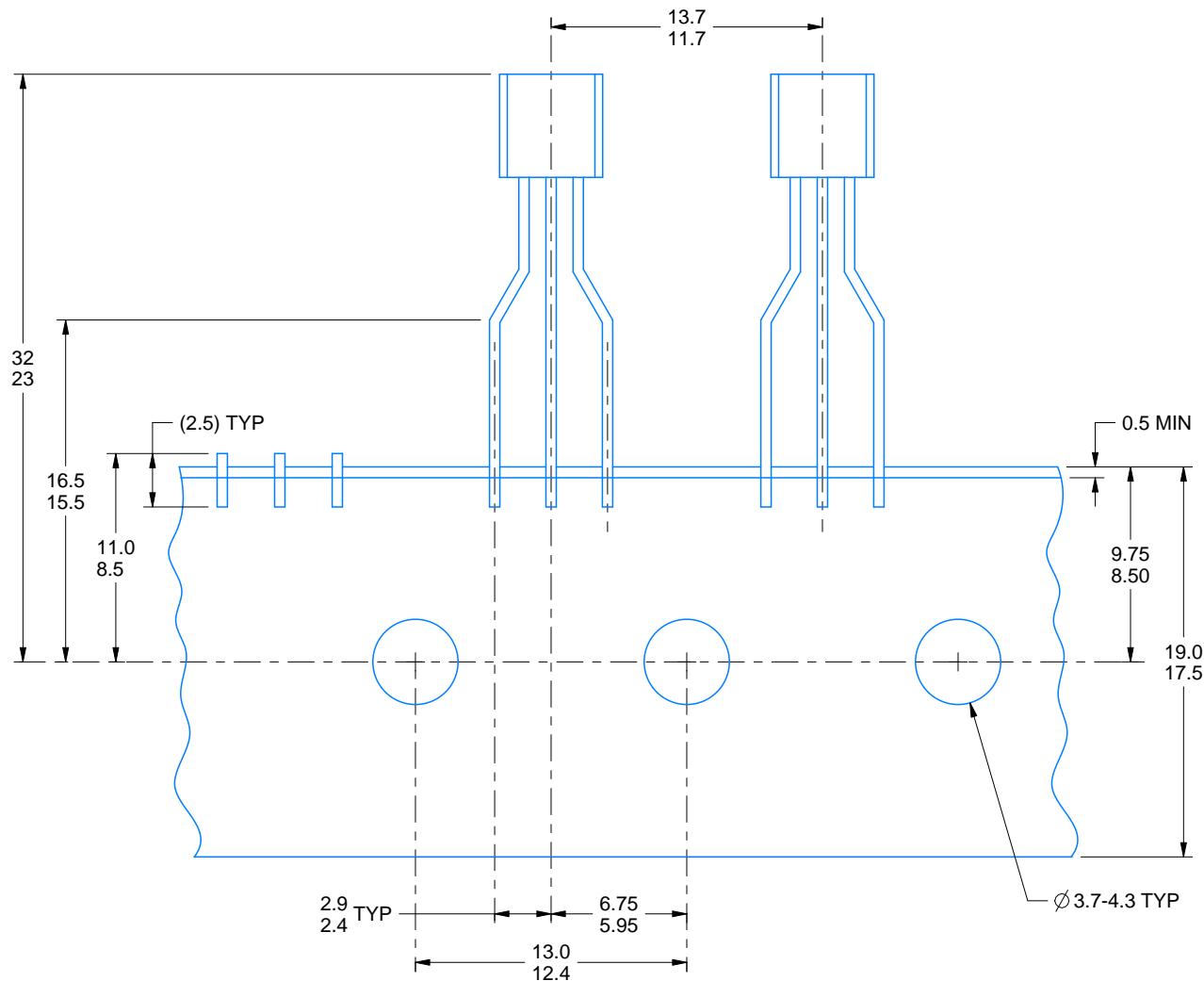
4215214/C 04/2025

TAPE SPECIFICATIONS

LP0003A

TO-92 - 5.34 mm max height

TO-92



FOR FORMED LEAD OPTION PACKAGE

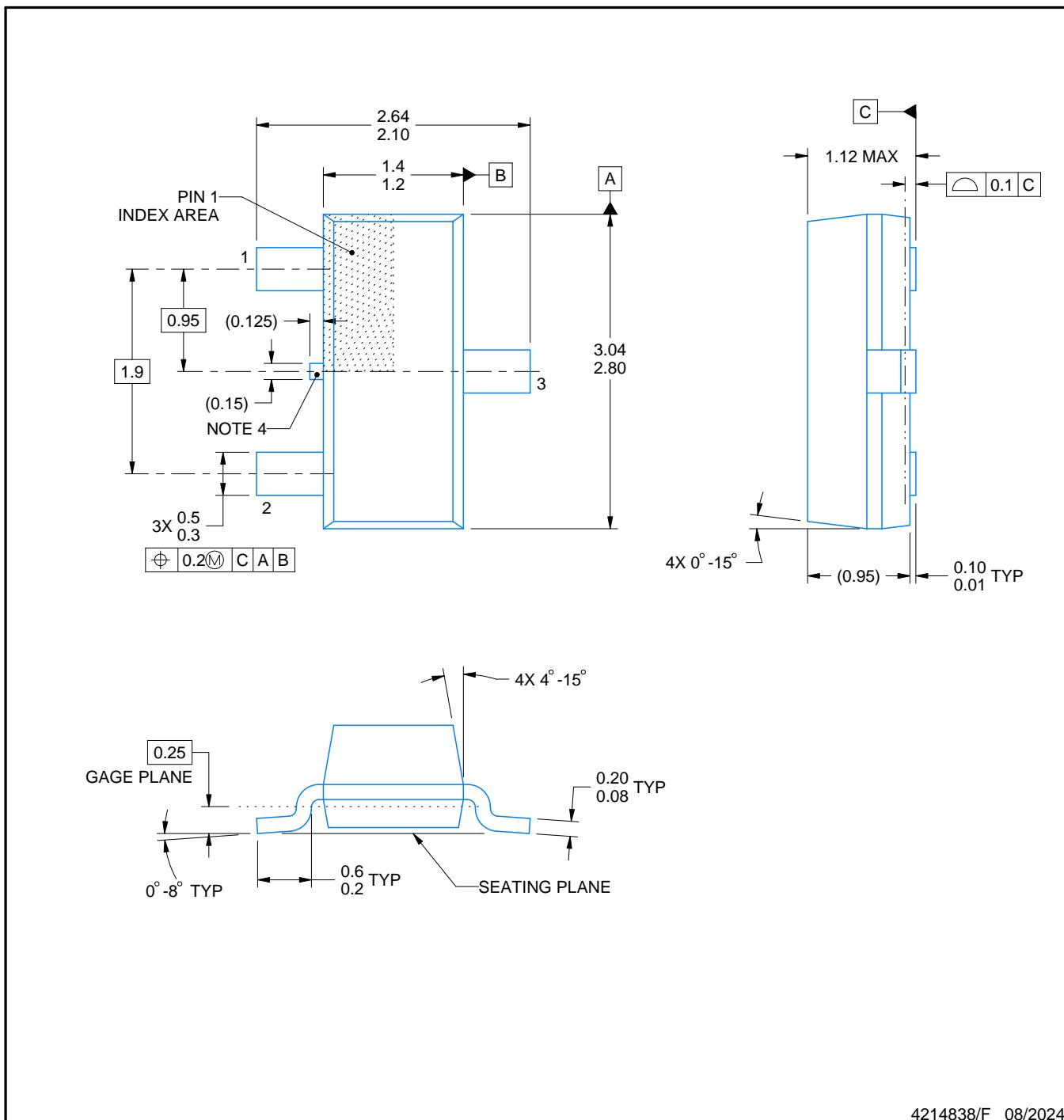
4215214/C 04/2025

PACKAGE OUTLINE

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



NOTES:

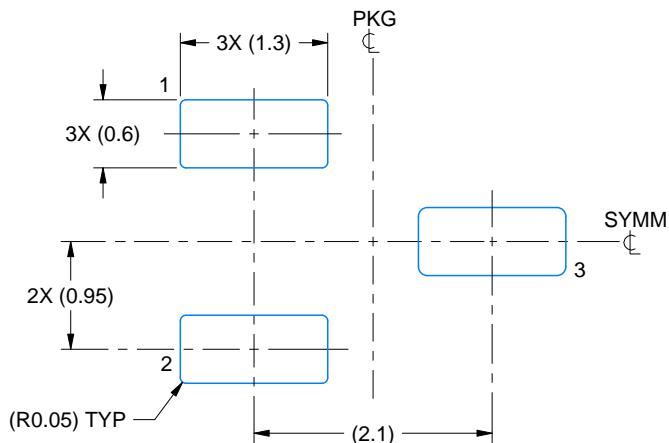
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
4. Support pin may differ or may not be present.
5. Body dimensions do not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.25mm per side

EXAMPLE BOARD LAYOUT

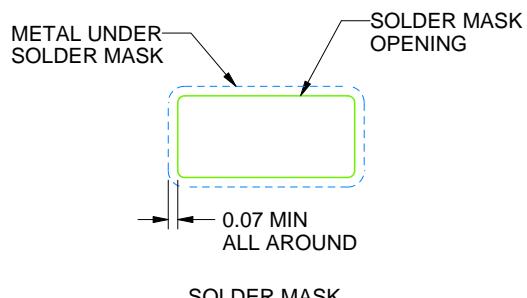
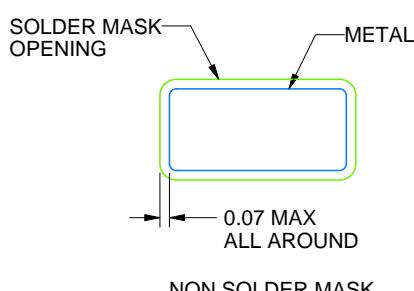
DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



LAND PATTERN EXAMPLE
SCALE:15X



SOLDER MASK DETAILS

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NOTES: (continued)

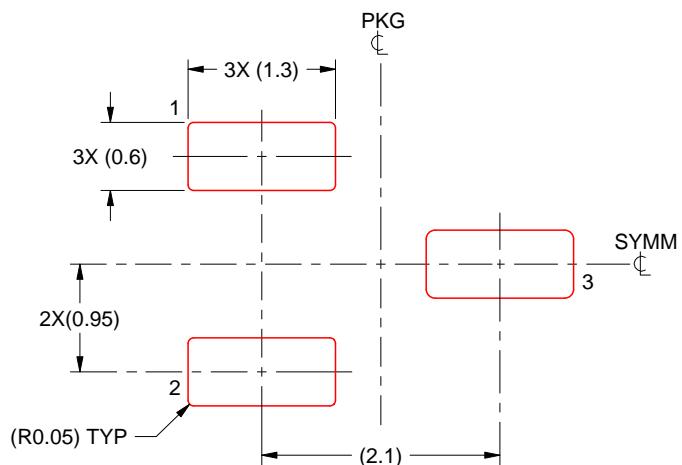
5. Publication IPC-7351 may have alternate designs.
6. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DBZ0003A

SOT-23 - 1.12 mm max height

SMALL OUTLINE TRANSISTOR



SOLDER PASTE EXAMPLE
BASED ON 0.125 THICK STENCIL
SCALE:15X

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NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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